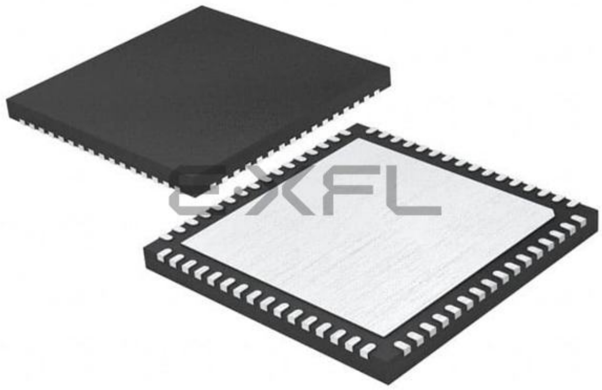

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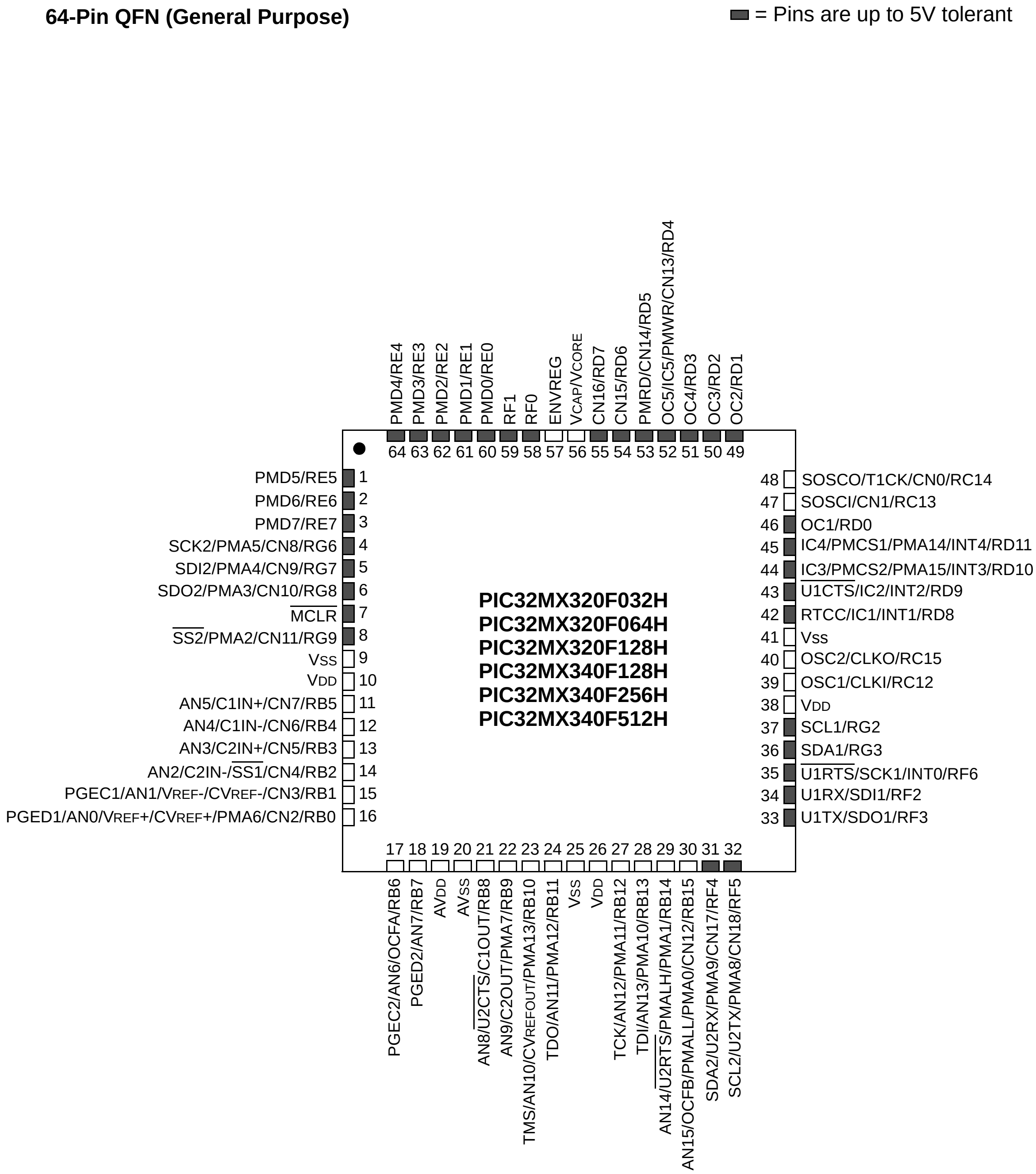
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	80MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	53
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-VQFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx440f128h-80v-mr

Pin Diagrams

64-Pin QFN (General Purpose)



Note: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

Pin Diagrams (Continued)

100-Pin TQFP (USB)

= Pins are up to 5V tolerant

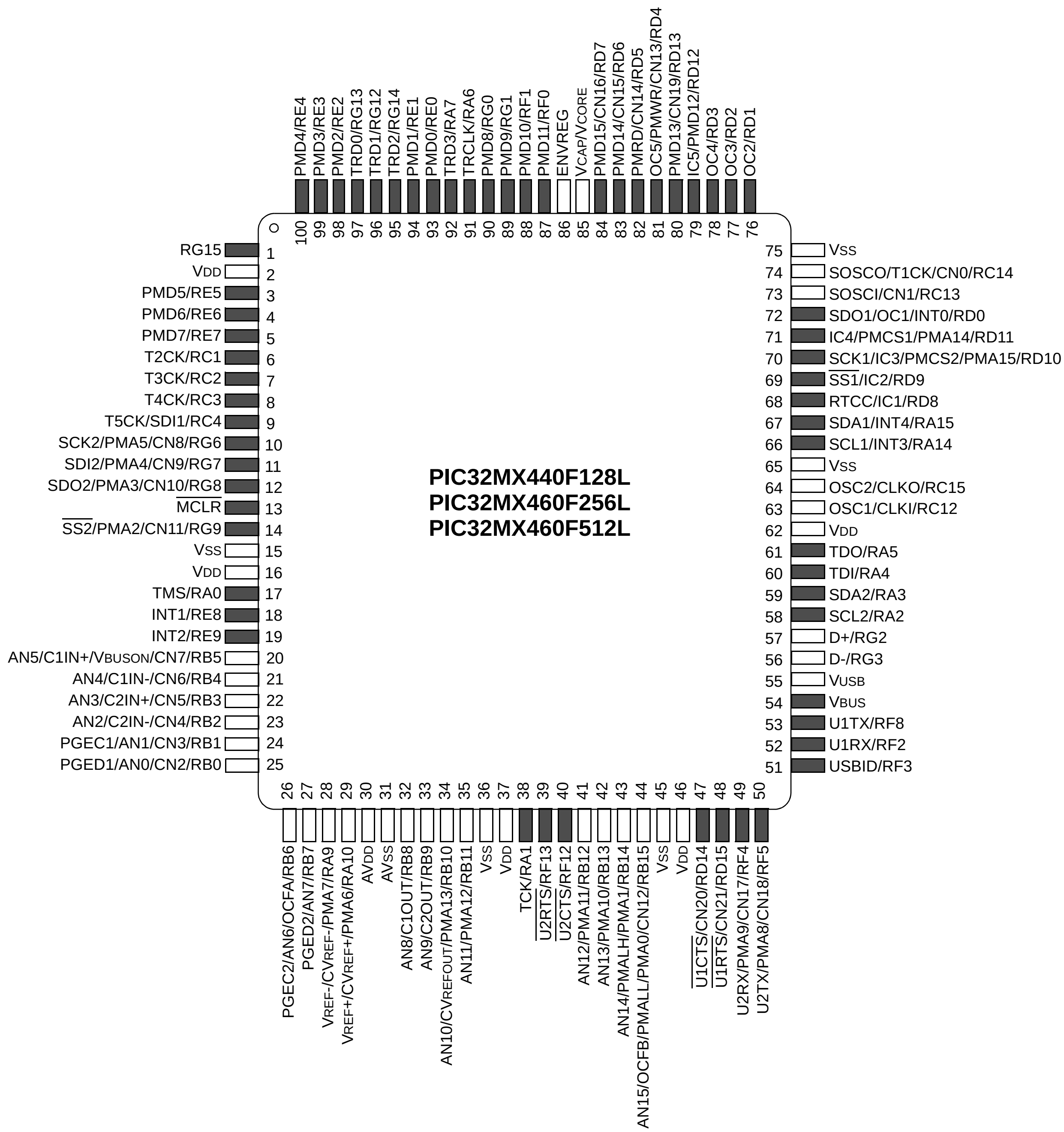


TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number(1)			Pin Type	Buffer Type	Description
	64-pin QFN/TQFP	100-pin TQFP	121-pin XBGA			
RD0	46	72	D9	I/O	ST	PORTD is a bidirectional I/O port.
RD1	49	76	A11	I/O	ST	
RD2	50	77	A10	I/O	ST	
RD3	51	78	B9	I/O	ST	
RD4	52	81	C8	I/O	ST	
RD5	53	82	B8	I/O	ST	
RD6	54	83	D7	I/O	ST	
RD7	55	84	C7	I/O	ST	
RD8	42	68	E9	I/O	ST	
RD9	43	69	E10	I/O	ST	
RD10	44	70	D11	I/O	ST	
RD11	45	71	C11	I/O	ST	
RD12	—	79	A9	I/O	ST	
RD13	—	80	D8	I/O	ST	
RD14	—	47	L9	I/O	ST	
RD15	—	48	K9	I/O	ST	
RE0	60	93	A4	I/O	ST	PORTE is a bidirectional I/O port.
RE1	61	94	B4	I/O	ST	
RE2	62	98	B3	I/O	ST	
RE3	63	99	A2	I/O	ST	
RE4	64	100	A1	I/O	ST	
RE5	1	3	D3	I/O	ST	
RE6	2	4	C1	I/O	ST	
RE7	3	5	D2	I/O	ST	
RE8	—	18	G1	I/O	ST	
RE9	—	19	G2	I/O	ST	
RF0	58	87	B6	I/O	ST	PORTF is a bidirectional I/O port.
RF1	59	88	A6	I/O	ST	
RF2	34	52	K11	I/O	ST	
RF3	33	51	K10	I/O	ST	
RF4	31	49	L10	I/O	ST	
RF5	32	50	L11	I/O	ST	
RF6	35	55	H9	I/O	ST	
RF7	—	54	H8	I/O	ST	
RF8	—	53	J10	I/O	ST	
RF12	—	40	K6	I/O	ST	
RF13	—	39	L6	I/O	ST	

Legend: CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; TTL = TTL input buffer; Analog = Analog input; O = Output; P = Power; I = Input

Note 1: Pin numbers are provided for reference only. See the **"Pin Diagrams"** section for device pin availability.

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number(1) 64-pin QFN/TQFP	Pin Number(1) 100-pin TQFP	Pin Number(1) 121-pin XBGA	Pin Type	Buffer Type	Description
RG0	—	90	A5	I/O	ST	PORTG is a bidirectional I/O port.
RG1	—	89	E6	I/O	ST	
RG6	4	10	E3	I/O	ST	
RG7	5	11	F4	I/O	ST	
RG8	6	12	F2	I/O	ST	
RG9	8	14	F3	I/O	ST	
RG12	—	96	C3	I/O	ST	
RG13	—	97	A3	I/O	ST	
RG14	—	95	C4	I/O	ST	
RG15	—	1	B2	I/O	ST	
RG2	37	57	H10	I	ST	PORTG input pins.
RG3	36	56	J11	I	ST	
T1CK	48	74	B11	I	ST	Timer1 external clock input.
T2CK	—	6	D1	I	ST	Timer2 external clock input.
T3CK	—	7	E4	I	ST	Timer3 external clock input.
T4CK	—	8	E2	I	ST	Timer4 external clock input.
T5CK	—	9	E1	I	ST	Timer5 external clock input.
$\overline{\text{U1CTS}}$	43	47	L9	I	ST	UART1 clear to send.
$\overline{\text{U1RTS}}$	35, 49	48	K9	O	—	UART1 ready to send.
U1RX	34, 50	52	K11	I	ST	UART1 receive.
U1TX	33, 51	51, 53	J10, K10	O	—	UART1 transmit.
$\overline{\text{U2CTS}}$	21	40	K6	I	ST	UART2 clear to send.
$\overline{\text{U2RTS}}$	29	39	L6	O	—	UART2 ready to send.
U2RX	31	49	L10	I	ST	UART2 receive.
U2TX	32	50	L11	O	—	UART2 transmit.
SCK1	35	55, 70	D11, H9	I/O	ST	Synchronous serial clock input/output for SPI1.
SDI1	34	9, 54	E1, H8	I	ST	SPI1 data in.
SDO1	33	53, 72	D9, J10	O	—	SPI1 data out.
$\overline{\text{SS1}}$	14	23, 69	E10, J2	I/O	ST	SPI1 slave synchronization or frame pulse I/O.
SCK2	4	10	E3	I/O	ST	Synchronous serial clock input/output for SPI2.
SDI2	5	11	F4	I	ST	SPI2 data in.
SDO2	6	12	F2	O	—	SPI2 data out.
$\overline{\text{SS2}}$	8	14	F3	I/O	ST	SPI2 slave synchronization or frame pulse I/O.
SCL1	37, 44	57, 66	E11, H10	I/O	ST	Synchronous serial clock input/output for I2C1.
SDA1	36, 43	56, 67	E8, J11	I/O	ST	Synchronous serial data input/output for I2C1.
SCL2	32	58	H11	I/O	ST	Synchronous serial clock input/output for I2C2.
SDA2	31	59	G10	I/O	ST	Synchronous serial data input/output for I2C2.

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
TTL = TTL input buffer

Note 1: Pin numbers are provided for reference only. See the **“Pin Diagrams”** section for device pin availability.

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number(1)			Pin Type	Buffer Type	Description
	64-pin QFN/TQFP	100-pin TQFP	121-pin XBGA			
TMS	23	17	G3	I	ST	JTAG Test mode select pin.
TCK	27	38	J6	I	ST	JTAG test clock input pin.
TDI	28	60	G11	I	ST	JTAG test data input pin.
TDO	24	61	G9	O	—	JTAG test data output pin.
RTCC	42	68	E9	O	—	Real-Time Clock Alarm Output.
CVREF-	15	28	L2	I	Analog	Comparator Voltage Reference (low).
CVREF+	16	29	K3	I	Analog	Comparator Voltage Reference (high).
CVREFOUT	23	34	L5	O	Analog	Comparator Voltage Reference Output.
C1IN-	12	21	H2	I	Analog	Comparator 1 Negative Input.
C1IN+	11	20	H1	I	Analog	Comparator 1 Positive Input.
C1OUT	21	32	K4	O	—	Comparator 1 Output.
C2IN-	14	23	J2	I	Analog	Comparator 2 Negative Input.
C2IN+	13	22	J1	I	Analog	Comparator 2 Positive Input.
C2OUT	22	33	L4	O	—	Comparator 2 Output.
PMA0	30	44	L8	I/O	TTL/ST	Parallel Master Port Address Bit 0 Input (Buffered Slave modes) and Output (Master modes).
PMA1	29	43	K7	I/O	TTL/ST	Parallel Master Port Address Bit 1 Input (Buffered Slave modes) and Output (Master modes).
PMA2	8	14	F3	O	—	Parallel Master Port Address (De-multiplexed Master Modes).
PMA3	6	12	F2	O	—	
PMA4	5	11	F4	O	—	
PMA5	4	10	E3	O	—	
PMA6	16	29	K3	O	—	
PMA7	22	28	L2	O	—	
PMA8	32	50	L11	O	—	
PMA9	31	49	L10	O	—	
PMA10	28	42	L7	O	—	
PMA11	27	41	J7	O	—	
PMA12	24	35	J5	O	—	
PMA13	23	34	L5	O	—	
PMA14	45	71	C11	O	—	
PMA15	44	70	D11	O	—	
PMCS1	45	71	C11	O	—	Parallel Master Port Chip Select 1 Strobe.
PMCS2	44	70	D11	O	—	Parallel Master Port Chip Select 2 Strobe.

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
TTL = TTL input buffer

Note 1: Pin numbers are provided for reference only. See the **"Pin Diagrams"** section for device pin availability.

3.0 CPU

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 2. "CPU"** (DS61113) of the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32). Resources for the MIPS32® M4K® Processor Core are available at: www.mips.com/products/cores/32-64-bit-cores/mips32-m4k/.

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The MIPS32® M4K® Processor Core is the heart of the PIC32MX3XX/4XX family processor. The CPU fetches instructions, decodes each instruction, fetches source operands, executes each instruction and writes the results of instruction execution to the proper destinations.

3.1 Features

- 5-stage pipeline
- 32-bit Address and Data Paths
- MIPS32 Enhanced Architecture (Release 2)
  - Multiply-Accumulate and Multiply-Subtract Instructions
  - Targeted Multiply Instruction
  - Zero/One Detect Instructions
  - `WAIT` Instruction
  - Conditional Move Instructions (`MOVN`, `MOVZ`)
  - Vectored interrupts
  - Programmable exception vector base
  - Atomic interrupt enable/disable
  - GPR shadow registers to minimize latency for interrupt handlers
  - Bit field manipulation instructions
- MIPS16e® Code Compression
  - 16-bit encoding of 32-bit instructions to improve code density
  - Special PC-relative instructions for efficient loading of addresses and constants
  - SAVE & RESTORE macro instructions for setting up and tearing down stack frames within subroutines
  - Improved support for handling 8 and 16-bit data types
- Simple Fixed Mapping Translation (FMT) mechanism
- Simple Dual Bus Interface
  - Independent 32-bit address and data busses
  - Transactions can be aborted to improve interrupt latency
- Autonomous Multiply/Divide Unit
  - Maximum issue rate of one 32x16 multiply per clock
  - Maximum issue rate of one 32x32 multiply every other clock
  - Early-in iterative divide. Minimum 11 and maximum 34 clock latency (dividend (*rs*) sign extension-dependent)
- Power Control
  - Minimum frequency: 0 MHz
  - Low-Power mode (triggered by `WAIT` instruction)
  - Extensive use of local gated clocks
- EJTAG Debug and Instruction Trace
  - Support for single stepping
  - Virtual instruction and data address/value
  - breakpoints
  - PC tracing with trace compression

FIGURE 3-1: MIPS® M4K® BLOCK DIAGRAM

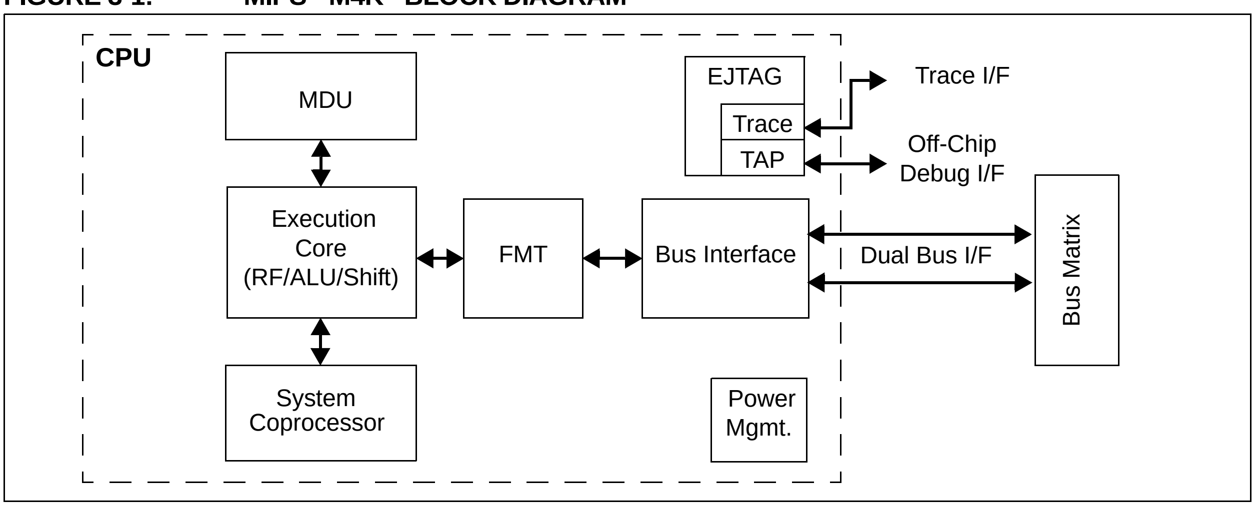


TABLE 4-9: OUTPUT COMPARE1-5 REGISTERS MAP(1)

Virtual Address (BF80_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
3000	OC1CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	OC32	OCFLT	OCTSEL	OCM<2:0>			0000
3010	OC1R	31:16	OC1R<31:0>																xxxx
		15:0																	xxxx
3020	OC1RS	31:16	OC1RS<31:0>																xxxx
		15:0																	xxxx
3200	OC2CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	OC32	OCFLT	OCTSEL	OCM<2:0>			0000
3210	OC2R	31:16	OC2R<31:0>																xxxx
		15:0																	xxxx
3220	OC2RS	31:16 15:0	OC2RS<31:0>																xxxx
																			xxxx
3400	OC3CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	OC32	OCFLT	OCTSEL	OCM<2:0>			0000
3410	OC3R	31:16	OC3R<31:0>																xxxx
		15:0																	xxxx
3420	OC3RS	31:16 15:0	OC3RS<31:0>																xxxx
																			xxxx
3600	OC4CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	OC32	OCFLT	OCTSEL	OCM<2:0>			0000
3610	OC4R	31:16	OC4R<31:0>																xxxx
		15:0																	xxxx
3620	OC4RS	31:16 15:0	OC4RS<31:0>																xxxx
																			xxxx
3800	OC5CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	OC32	OCFLT	OCTSEL	OCM<2:0>			0000
3810	OC5R	31:16	OC5R<31:0>																xxxx
		15:0																	xxxx
3820	OC5RS	31:16	OC5RS<31:0>																xxxx
		15:0																	xxxx

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 "CLR, SET and INV Registers"** for more information.

TABLE 4-11: UART1-2 REGISTERS MAP

Virtual Address (BF80_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
6000	U1MODE(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	IREN	RTSMD	—	UEN<1:0>		WAKE	LPBACK	ABAUD	RXINV	BRGH	PDSEL<1:0>		STSEL	0000
6010	U1STA(1)	31:16	—	—	—	—	—	—	—	ADM_EN	ADDR<7:0>								0000
		15:0	UTXISEL<1:0>		UTXINV	URXEN	UTXBRK	UTXEN	UTXBF	TRMT	URXISEL<1:0>		ADDEN	RIDLE	PERR	FERR	OERR	URXDA	0110
6020	U1TXREG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	TX8	Transmit Register								0000
6030	U1RXREG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	RX8	Receive Register								0000
6040	U1BRG(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	BRG<15:0>																0000
6200	U2MODE(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	IREN	RTSMD	—	UEN<1:0>		WAKE	LPBACK	ABAUD	RXINV	BRGH	PDSEL<1:0>		STSEL	0000
6210	U2STA(1)	31:16	—	—	—	—	—	—	—	ADM_EN	ADDR<7:0>								0000
		15:0	UTXISEL<1:0>		UTXINV	URXEN	UTXBRK	UTXEN	UTXBF	TRMT	URXISEL<1:0>		ADDEN	RIDLE	PERR	FERR	OERR	URXDA	0110
6220	U2TXREG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	TX8	Transmit Register								0000
6230	U2RXREG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	RX8	Receive Register								0000
6240	U2BRG(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	BRG<15:0>																0000

Legend: x = unknown value on Reset, — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

Note 1: This register has corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.

TABLE 4-40: RTCC REGISTERS MAP(1)

Virtual Address (BF80_#)	Register Name	Bit Range	31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	All Resets
0200	RTCCON	31:16	—	—	—	—	—	—	CAL<11:0>										0000
		15:0	ON	—	SIDL	—	—	—	—	—	RTSECSEL	RTCCLKON	—	—	RTCWREN	RTCSYNC	HALFSEC	RTCOE	0000
0210	RTCALRM	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ALRMEN	CHIME	PIV	ALRMSYNC	AMASK<3:0>				ARPT<7:0>								0000
0220	RTCTIME	31:16	HR10<3:0>				HR01<3:0>				MIN10<3:0>				MIN01<3:0>				xxxx
		15:0	SEC10<3:0>				SEC01<3:0>				—	—	—	—	—	—	—	—	xx00
0230	RTCDATE	31:16	YEAR10<3:0>				YEAR01<3:0>				MONTH10<3:0>				MONTH01<3:0>				xxxx
		15:0	DAY10<3:0>				DAY01<3:0>				—	—	—	—	WDAY01<3:0>				xx0x
0240	ALRMTIME	31:16	MIN10<3:0>				MIN01<3:0>				MIN10<3:0>				MIN01<3:0>				xxxx
		15:0	SEC10<3:0>				SEC01<3:0>				—	—	—	—	—	—	—	—	xx00
0250	ALRMDATE	31:16	—	—	—	—	—	—	—	—	MONTH10<3:0>				MONTH01<3:0>				00xx
		15:0	DAY10<3:0>				DAY01<3:0>				—	—	—	—	WDAY01<3:0>				xx0x

Legend: x = unknown value on Reset, — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.

TABLE 4-41: DEVCFG: DEVICE CONFIGURATION WORD SUMMARY

Virtual Address (BFC0_#)	Register Name	Bit Range	31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	All Resets
2FF0	DEVCFG3	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	xxxx
		15:0	USERID15	USERID14	USERID13	USERID12	USERID11	USERID10	USERID9	USERID8	USERID7	USERID6	USERID5	USERID4	USERID3	USERID2	USERID1	USERID0	xxxx
2FF4	DEVCFG2	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	FPLLODIV<2:0>			xxxx
		15:0	UPLLEN(1)	—	—	—	—	UPLLIDIV<2:0>(1)			—	FPLLMUL<2:0>			—	FPLLIDIV<2:0>			xxxx
2FF8	DEVCFG1	31:16	—	—	—	—	—	—	—	—	FWDTEN	—	—	WDTPS<4:0>					xxxx
		15:0	FCKSM<1:0>		FPBDIV<1:0>		—	OSCIOFNC	POSCMOD<1:0>		IESO	—	FSOSCEN	—	—	FNOSC<2:0>			xxxx
2FFC	DEVCFG0	31:16	—	—	—	CP	—	—	—	BWP	—	—	—	—	PWP19	PWP18	PWP17	PWP16	xxxx
		15:0	PWP15	PWP14	PWP13	PWP12	—	—	—	—	—	—	—	—	ICESEL	—	DEBUG<1:0>		xxxx

Legend: x = unknown value on Reset, — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

Note 1: These bits are only available on PIC32MX4XX devices.

5.0 FLASH PROGRAM MEMORY

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 5. “Flash Program Memory”** (DS61121) of the *“PIC32 Family Reference Manual”*, which is available from the Microchip web site (www.microchip.com/PIC32).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

PIC32MX3XX/4XX devices contain an internal program Flash memory for executing user code. There are three methods by which the user can program this memory:

- Run-Time Self Programming (RTSP)
- In-Circuit Serial Programming™ (ICSP™)
- EJTAG Programming

RTSP is performed by software executing from either Flash or RAM memory. EJTAG is performed using the EJTAG port of the device and a EJTAG capable programmer. ICSP is performed using a serial data connection to the device and allows much faster programming times than RTSP. RTSP techniques are described in this chapter. The ICSP and EJTAG methods are described in the “*PIC32MX Flash Programming Specification*” (DS61145), which can be downloaded from the Microchip web site.

Note: Flash LVD Delay (LVDstartup) must be taken into account between setting up and executing any Flash command operation. See Example 5-1 for a code example to set up and execute a Flash command operation.

EXAMPLE 5-1:

```
NVMCON = 0x4004;          // Enable and configure for erase operation
Wait(delay);              // Delay for 6 µs for LVDstartup

NVMKEY = 0xAA996655;
NVMKEY = 0x556699AA;
NVMCONSET = 0x8000;       // Initiate operation

while(NVMCONbits.WR==1);  // Wait for current operation to complete
```


TABLE 7-1: INTERRUPT IRQ AND VECTOR LOCATION

Interrupt Source(1)	IRQ	Vector Number	Interrupt Bit Location			
Highest Natural Order Priority			Flag	Enable	Priority	Subpriority
CT – Core Timer Interrupt	0	0	IFS0<0>	IEC0<0>	IPC0<4:2>	IPC0<1:0>
CS0 – Core Software Interrupt 0	1	1	IFS0<1>	IEC0<1>	IPC0<12:10>	IPC0<9:8>
CS1 – Core Software Interrupt 1	2	2	IFS0<2>	IEC0<2>	IPC0<20:18>	IPC0<17:16>
INT0 – External Interrupt 0	3	3	IFS0<3>	IEC0<3>	IPC0<28:26>	IPC0<25:24>
T1 – Timer1	4	4	IFS0<4>	IEC0<4>	IPC1<4:2>	IPC1<1:0>
IC1 – Input Capture 1	5	5	IFS0<5>	IEC0<5>	IPC1<12:10>	IPC1<9:8>
OC1 – Output Compare 1	6	6	IFS0<6>	IEC0<6>	IPC1<20:18>	IPC1<17:16>
INT1 – External Interrupt 1	7	7	IFS0<7>	IEC0<7>	IPC1<28:26>	IPC1<25:24>
T2 – Timer2	8	8	IFS0<8>	IEC0<8>	IPC2<4:2>	IPC2<1:0>
IC2 – Input Capture 2	9	9	IFS0<9>	IEC0<9>	IPC2<12:10>	IPC2<9:8>
OC2 – Output Compare 2	10	10	IFS0<10>	IEC0<10>	IPC2<20:18>	IPC2<17:16>
INT2 – External Interrupt 2	11	11	IFS0<11>	IEC0<11>	IPC2<28:26>	IPC2<25:24>
T3 – Timer3	12	12	IFS0<12>	IEC0<12>	IPC3<4:2>	IPC3<1:0>
IC3 – Input Capture 3	13	13	IFS0<13>	IEC0<13>	IPC3<12:10>	IPC3<9:8>
OC3 – Output Compare 3	14	14	IFS0<14>	IEC0<14>	IPC3<20:18>	IPC3<17:16>
INT3 – External Interrupt 3	15	15	IFS0<15>	IEC0<15>	IPC3<28:26>	IPC3<25:24>
T4 – Timer4	16	16	IFS0<16>	IEC0<16>	IPC4<4:2>	IPC4<1:0>
IC4 – Input Capture 4	17	17	IFS0<17>	IEC0<17>	IPC4<12:10>	IPC4<9:8>
OC4 – Output Compare 4	18	18	IFS0<18>	IEC0<18>	IPC4<20:18>	IPC4<17:16>
INT4 – External Interrupt 4	19	19	IFS0<19>	IEC0<19>	IPC4<28:26>	IPC4<25:24>
T5 – Timer5	20	20	IFS0<20>	IEC0<20>	IPC5<4:2>	IPC5<1:0>
IC5 – Input Capture 5	21	21	IFS0<21>	IEC0<21>	IPC5<12:10>	IPC5<9:8>
OC5 – Output Compare 5	22	22	IFS0<22>	IEC0<22>	IPC5<20:18>	IPC5<17:16>
SPI1E – SPI1 Fault	23	23	IFS0<23>	IEC0<23>	IPC5<28:26>	IPC5<25:24>
SPI1TX – SPI1 Transfer Done	24	23	IFS0<24>	IEC0<24>	IPC5<28:26>	IPC5<25:24>
SPI1RX – SPI1 Receive Done	25	23	IFS0<25>	IEC0<25>	IPC5<28:26>	IPC5<25:24>
U1E – UART1 Error	26	24	IFS0<26>	IEC0<26>	IPC6<4:2>	IPC6<1:0>
U1RX – UART1 Receiver	27	24	IFS0<27>	IEC0<27>	IPC6<4:2>	IPC6<1:0>
U1TX – UART1 Transmitter	28	24	IFS0<28>	IEC0<28>	IPC6<4:2>	IPC6<1:0>
I2C1B – I2C1 Bus Collision Event	29	25	IFS0<29>	IEC0<29>	IPC6<12:10>	IPC6<9:8>
I2C1S – I2C1 Slave Event	30	25	IFS0<30>	IEC0<30>	IPC6<12:10>	IPC6<9:8>
I2C1M – I2C1 Master Event	31	25	IFS0<31>	IEC0<31>	IPC6<12:10>	IPC6<9:8>
CN – Input Change Interrupt	32	26	IFS1<0>	IEC1<0>	IPC6<20:18>	IPC6<17:16>
AD1 – ADC1 Convert Done	33	27	IFS1<1>	IEC1<1>	IPC6<28:26>	IPC6<25:24>
PMP – Parallel Master Port	34	28	IFS1<2>	IEC1<2>	IPC7<4:2>	IPC7<1:0>
CMP1 – Comparator Interrupt	35	29	IFS1<3>	IEC1<3>	IPC7<12:10>	IPC7<9:8>
CMP2 – Comparator Interrupt	36	30	IFS1<4>	IEC1<4>	IPC7<20:18>	IPC7<17:16>

Note 1: Not all interrupt sources are available on all devices. See **TABLE 1: "PIC32MX General Purpose – Features"** and **TABLE 2: "PIC32MX USB – Features"** for available peripherals.

9.0 PREFETCH CACHE

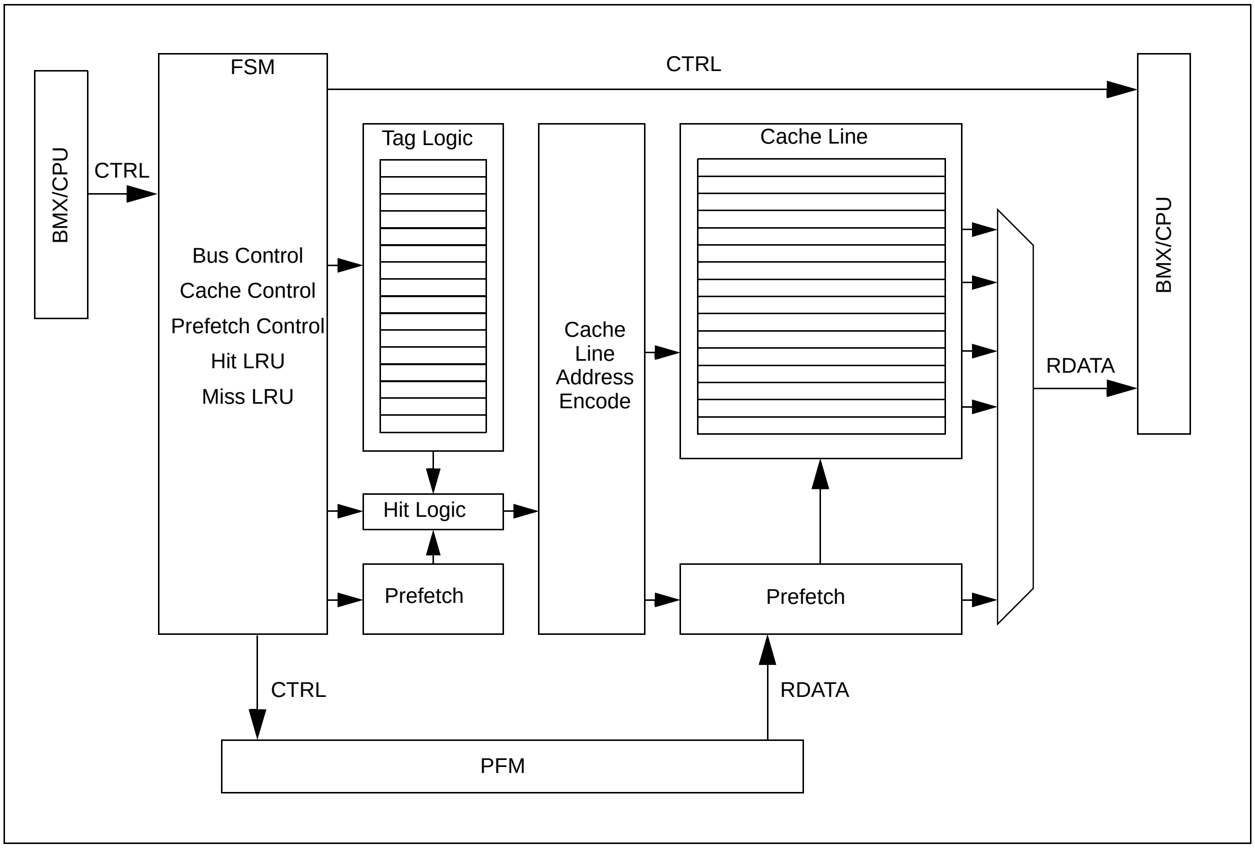
> **Note 1:** This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 4. "Prefetch Cache"** (DS61119) of the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32).
>
> **2:** Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

Prefetch cache increases performance for applications executing out of the cacheable program Flash memory regions by implementing instruction caching, constant data caching and instruction prefetching.

9.1 Features

- 16 Fully Associative Lockable Cache Lines
- 16-byte Cache Lines
- Up to four Cache Lines Allocated to Data
- Two Cache Lines with Address Mask to hold repeated instructions
- Pseudo LRU replacement policy
- All Cache Lines are software writable
- 16-byte parallel memory fetch
- Predictive Instruction Prefetch

FIGURE 9-1: PREFETCH MODULE BLOCK DIAGRAM



12.1 Parallel I/O (PIO) Ports

All port pins have three registers (TRIS, LAT and PORT) that are directly associated with their operation.

TRIS is a data direction or tri-state control register that determines whether a digital pin is an input or an output. Setting a TRISx register bit = 1 configures the corresponding I/O pin as an input; setting a TRISx register bit = 0 configures the corresponding I/O pin as an output. All port I/O pins are defined as inputs after a device Reset. Certain I/O pins are shared with analog peripherals and default to analog inputs after a device Reset.

PORT is a register used to read the current state of the signal applied to the port I/O pins. Writing to a PORTx register performs a write to the port's latch, LATx register, latching the data to the port's I/O pins.

LAT is a register used to write data to the port I/O pins. The LATx latch register holds the data written to either the LATx or PORTx registers. Reading the LATx latch register reads the last value written to the corresponding port or latch register.

Not all port I/O pins are implemented on some devices, therefore, the corresponding PORTx, LATx and TRISx register bits will read as zeros.

12.1.1 CLR, SET AND INV REGISTERS

Every I/O module register has a corresponding CLR (clear), SET (set) and INV (invert) register designed to provide fast atomic bit manipulations. As the name of the register implies, a value written to a SET, CLR or INV register effectively performs the implied operation, but only on the corresponding base register and only bits specified as '1' are modified. Bits specified as '0' are not modified.

Reading SET, CLR and INV registers returns undefined values. To see the affects of a write operation to a SET, CLR or INV register, the base register must be read.

Note:	Using a PORTxINV register to toggle a bit is recommended because the operation is performed in hardware atomically, using fewer instructions as compared to the traditional read-modify-write method shown below: PORTC ^= 0x0001;

12.1.2 DIGITAL INPUTS

Pins are configured as digital inputs by setting the corresponding TRIS register bits = 1. When configured as inputs, they are either TTL buffers or Schmitt Triggers. Several digital pins share functionality with analog inputs and default to the analog inputs at POR. Setting the corresponding bit in the AD1PCFG register = 1 enables the pin as a digital pin.

The maximum input voltage allowed on the input pins is the same as the maximum V_{IH} specification. Refer to **Section 29.0 "Electrical Characteristics"** for V_{IH} specification details.

Note:	Analog levels on any pin that is defined as a digital input (including the ANx pins) may cause the input buffer to consume current that exceeds the device specifications.

12.1.3 ANALOG INPUTS

Certain pins can be configured as analog inputs used by the ADC and Comparator modules. Setting the corresponding bits in the AD1PCFG register = 0 enables the pin as an analog input pin and must have the corresponding TRIS bit set = 1 (input). If the TRIS bit is cleared = 0 (output), the digital output level (V_{OH} or V_{OL}) will be converted. Any time a port I/O pin is configured as analog, its digital input is disabled and the corresponding PORTx register bit will read '0'. The AD1PCFG Register has a default value of 0x0000; therefore, all pins that share ANx functions are analog (not digital) by default.

12.1.4 DIGITAL OUTPUTS

Pins are configured as digital outputs by setting the corresponding TRIS register bits = 0. When configured as digital outputs, these pins are CMOS drivers or can be configured as open drain outputs by setting the corresponding bits in the ODCx Open-Drain Configuration register.

The open-drain feature allows the generation of outputs higher than V_{DD} (e.g., 5V) on any desired 5V tolerant pins by using external pull-up resistors. The maximum open-drain voltage allowed is the same as the maximum V_{IH} specification.

See the **"Pin Diagrams"** section for the available pins and their functionality.

12.1.5 ANALOG OUTPUTS

Certain pins can be configured as analog outputs, such as the CV_{REF} output voltage used by the comparator module. Configuring the Comparator Reference module to provide this output will present the analog output voltage on the pin, independent of the TRIS register setting for the corresponding pin.

12.1.6 INPUT CHANGE NOTIFICATION

The input change notification function of the I/O ports (CNx) allows devices to generate interrupt requests in response to change of state on selected pin.

Each CNx pin also has a weak pull-up, which acts as a current source connected to the pin. The pull-ups are enabled by setting corresponding bit in CNPUE register.

The processor will exit, or 'wake-up', from Sleep on one of the following events:

- On any interrupt from an enabled source that is operating in Sleep. The interrupt priority must be greater than the current CPU priority.
- On any form of device Reset.
- On a WDT time-out. See **Section 26.2 "Watchdog Timer (WDT)"**.

If the interrupt priority is lower than or equal to current priority, the CPU will remain halted, but the PBCLK will start running and the device will enter into Idle mode.

Note:	There is no FRZ mode for this module.

25.3.2 IDLE MODE

In the Idle mode, the CPU is halted but the System clock (SYSCLK) source is still enabled. This allows peripherals to continue operation when the CPU is halted. Peripherals can be individually configured to halt when entering Idle by setting their respective SIDL bit. Latency when exiting Idle mode is very low due to the CPU oscillator source remaining active.

Note:	Changing the PBCLK divider ratio requires recalculation of peripheral timing. For example, assume the UART is configured for 9600 baud with a PB clock ratio of 1:1 and a POSC of 8 MHz. When the PB clock divisor of 1:2 is used, the input frequency to the baud clock is cut in half; therefore, the baud rate is reduced to 1/2 its former value. Due to numeric truncation in calculations (such as the baud rate divisor), the actual baud rate may be a tiny percentage different than expected. For this reason, any timing calculation required for a peripheral should be performed with the new PB clock frequency instead of scaling the previous value based on a change in PB divisor ratio. Oscillator start-up and PLL lock delays are applied when switching to a clock source that was disabled and that uses a crystal and/or the PLL. For example, assume the clock source is switched from POSC to LPRC just prior to entering Sleep in order to save power. No oscillator start-up delay would be applied when exiting Idle. However, when switching back to POSC, the appropriate PLL and/or oscillator startup/lock delays would be applied.

The device enters Idle mode when the SLPEN (OSCCON<4>) bit is clear and a `WAIT` instruction is executed.

The processor will wake or exit from Idle mode on the following events:

- On any interrupt event for which the interrupt source is enabled. The priority of the interrupt event must be greater than the current priority of CPU. If the priority of the interrupt event is lower than or equal to current priority of CPU, the CPU will remain halted and the device will remain in Idle mode.
- On any source of device Reset.
- On a WDT time-out interrupt. See **Section 26.2 "Watchdog Timer (WDT)"**.

25.3.3 PERIPHERAL BUS SCALING METHOD

Most of the peripherals on the device are clocked using the PBCLK. The peripheral bus can be scaled relative to the SYSCLK to minimize the dynamic power consumed by the peripherals. The PBCLK divisor is controlled by PBDIV<1:0> (OSCCON<20:19>), allowing SYSCLK-to-PBCLK ratios of 1:1, 1:2, 1:4 and 1:8. All peripherals using PBCLK are affected when the divisor is changed. Peripherals such as USB, Interrupt Controller, DMA, Bus Matrix and Prefetch Cache are clocked directly from SYSCLK, as a result, they are not affected by PBCLK divisor changes

Changing the PBCLK divisor affects:

- The CPU to peripheral access latency. The CPU has to wait for next PBCLK edge for a read to complete. In 1:8 mode this results in a latency of one to seven SYSCLKs.
- The power consumption of the peripherals. Power consumption is directly proportional to the frequency at which the peripherals are clocked. The greater the divisor, the lower the power consumed by the peripherals.

To minimize dynamic power the PB divisor should be chosen to run the peripherals at the lowest frequency that provides acceptable system performance. When selecting a PBCLK divider, peripheral clock requirements such as baud rate accuracy should be taken into account. For example, the UART peripheral may not be able to achieve all baud rate values at some PBCLK divider depending on the SYSCLK value.

TABLE 29-24: TIMER2, 3, 4, 5 EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS				Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	Symbol	Characteristics[1]		Min.	Max.	Units	Conditions	
TB10	TTXH	TxCK High Time	Synchronous, with prescaler	[(12.5 ns or 1TPB)/N] + 25 ns	—	ns	Must also meet parameter TB15.	N = prescale value (1, 2, 4, 8, 16, 32, 64, 256)
TB11	TTXL	TxCK Low Time	Synchronous, with prescaler	[(12.5 ns or 1TPB)/N] + 25 ns	—	ns	Must also meet parameter TB15.	
TB15	TTXP	TxCK Input Period	Synchronous, with prescaler	[(Greater of 25 ns or 2 TPB)/N] + 30 ns	—	ns	VDD > 2.7V	
				[(Greater of 25 ns or 2 TPB)/N] + 50 ns	—	ns	VDD < 2.7V	—
TB20	TCKEXTMRL	Delay from External TxCK Clock Edge to Timer Increment		—	1	TPB	—	

Note 1: These parameters are characterized, but not tested in manufacturing.

TABLE 29-40: OTG ELECTRICAL SPECIFICATIONS

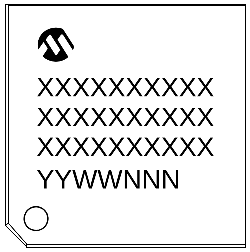
AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics[1]**	**Min.**	**Typ**	**Max.**	**Units**	**Conditions**
USB313	V_{USB}	USB Voltage	3.0	—	3.6	V	Voltage on V_{USB} must be in this range for proper USB operation.
USB315	V_{ILUSB}	Input Low Voltage for USB Buffer	—	—	0.8	V	—
USB316	V_{IHUSB}	Input High Voltage for USB Buffer	2.0	—	—	V	—
USB318	V_{DIFS}	Differential Input Sensitivity	—	—	0.2	V	The difference between D+ and D- must exceed this value while VCM is met.
USB319	VCM	Differential Common Mode Range	0.8	—	2.5	V	—
USB320	Z_{OUT}	Driver Output Impedance	28.0	—	44.0	Ω	—
USB321	V_{OL}	Voltage Output Low	0.0	—	0.3	V	1.5 kΩ load connected to 3.6V.
USB322	V_{OH}	Voltage Output High	2.8	—	3.6	V	1.5 kΩ load connected to ground.

Note 1: These parameters are characterized, but not tested in manufacturing.

30.0 PACKAGING INFORMATION

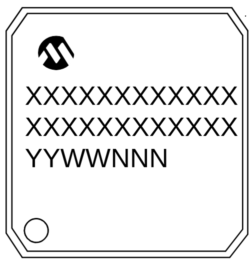
30.1 Package Marking Information

64-Lead TQFP (10x10x1 mm)



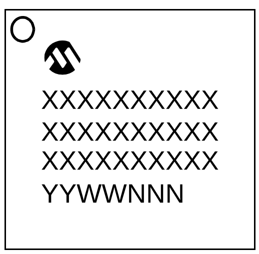
Example

100-Lead TQFP (12x12x1 mm)

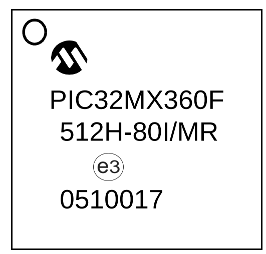


Example

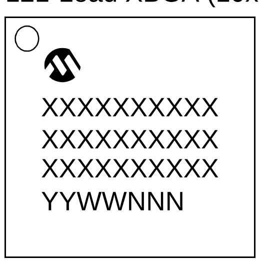
64-Lead QFN (9x9x0.9 mm)



Example



121-Lead XBGA (10x10x1.1 mm)



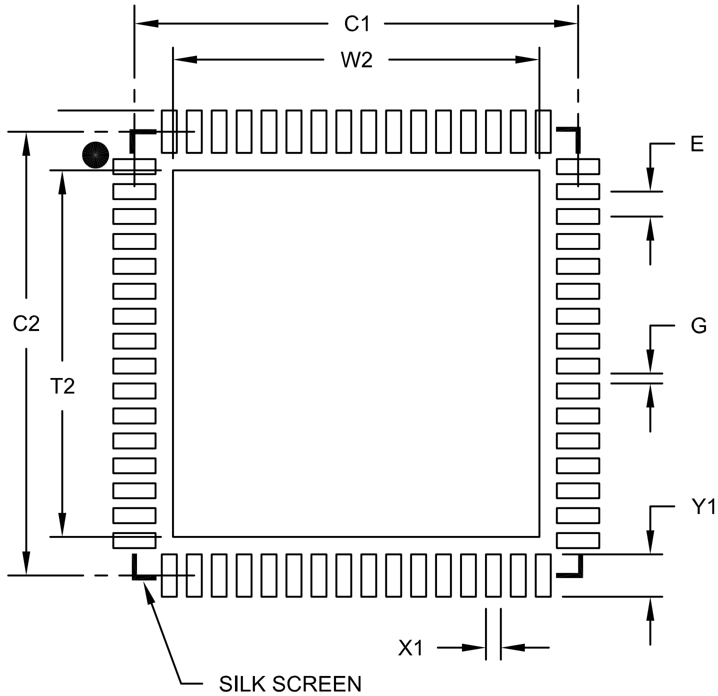
Example

Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
		Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

64-Lead Plastic Quad Flat, No Lead Package (MR) – 9x9x0.9 mm Body [QFN]
With 0.40 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Optional Center Pad Width	W2			7.35
Optional Center Pad Length	T2			7.35
Contact Pad Spacing	C1		8.90	
Contact Pad Spacing	C2		8.90	
Contact Pad Width (X64)	X1			0.30
Contact Pad Length (X64)	Y1			0.85
Distance Between Pads	G	0.20		

Notes:

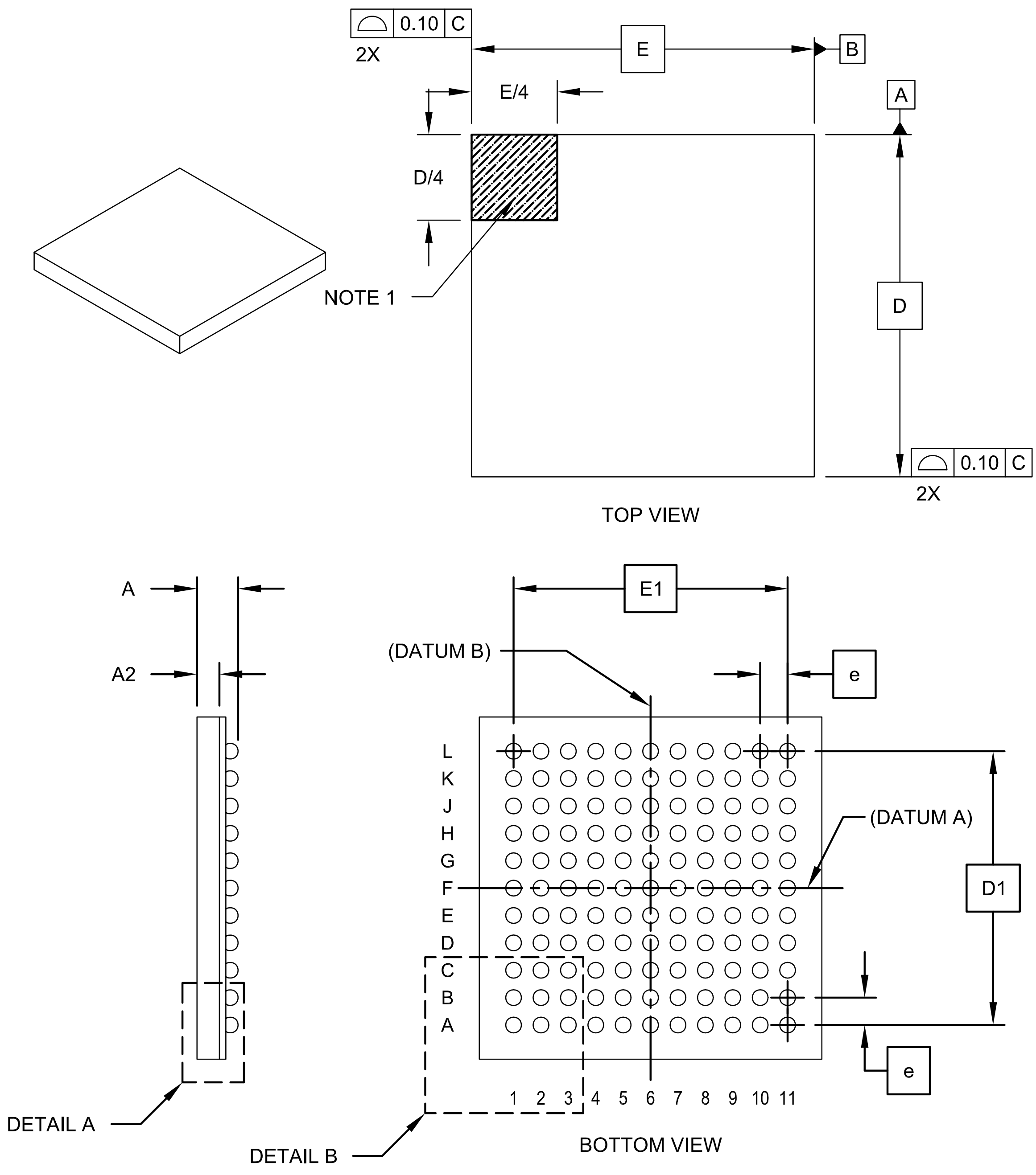
1. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2149A

121-Lead Plastic Thin Profile Ball Grid Array (BG) - 10x10x1.10 mm Body [XBGA]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-148B Sheet 1 of 2

Revision G (April 2010)

The revision includes the following global update:

- Added Note 2 to the shaded table that appears at the beginning of each chapter. This new note provides information regarding the availability of registers and their associated bits.

This revision also includes minor typographical and formatting changes throughout the data sheet text. Major updates are referenced by their respective section in the following table.

TABLE A-2: MAJOR SECTION UPDATES

Section Name	Update Description
“High-Performance, General Purpose and USB 32-bit Flash Microcontrollers”	Updated the crystal oscillator range to 3 MHz to 25 MHz (see **Peripheral Features:**) Added the 121-pin Ball Grid Array (XBGA) pin diagram. Updated Table 1: “PIC32MX General Purpose – Features” and Table 2: “PIC32MX USB – Features” Added the following tables: - Table 3: “Pin Names: PIC32MX320F128L, PIC32MX340F128L, and PIC32MX360F128L, and PIC32MX360F512L Devices”, - Table 4: “Pin Names: PIC32MX440F128L, PIC32MX460F256L and PIC32MX460F512L Devices” Updated the following pins as 5V tolerant: - 64-pin QFN (USB): Pin 34 (VBUS), Pin 36 (D-/RG3) and Pin 37 (D+/RG2) - 64-pin TQFP (USB): Pin 34 (Vbus), Pin 36 (D-/RG3), Pin 37 (D+/RG2) and Pin 42 (IC1/RTCC/INT1/RD8) - 100-pin TQFP (USB): Pin 54 (VBUS), Pin 56 (D-/RG3) and Pin 57 (D+/RG2)
Section 1.0 “Device Overview”	Updated the Pinout I/O Descriptions table to include the device pin numbers (see Table 1-1)
Section 2.0 “Guidelines for Getting Started with 32-bit Microcontrollers”	Updated the Ohm value for the low-ESR capacitor from less than 5 to less than 1 (see **Section 2.3.1 “Internal Regulator Mode”**). Labeled the capacitor on the VCAP/VDDCORE pin as CEFC in Figure 2-1. Changed 10 µF capacitor to CEFC capacitor in **Section 2.3 “Capacitor on Internal Voltage Regulator (VCAP/VCORE)”**.
Section 4.0 “Memory Organization”	Updated all register map tables to include the “All Resets” column. Separated the PORT register maps into individual tables (see Table 4-21 through Table 4-34). In addition, formatting changes were made to improve readability.
Section 12.0 “I/O Ports”	Updated the second paragraph of **Section 12.1.2 “Digital Inputs”** and removed Table 12-1.
Section 22.0 “10-bit Analog-to-Digital Converter (ADC)”	Updated the ADC Conversion Clock Period Block Diagram (see Figure 22-2).
Section 26.0 “Special Features”	Extensive updates were made to **Section 26.2 “Watchdog Timer (WDT)”** and **Section 26.3 “On-Chip Voltage Regulator”**.

